# 25K808, 25K808A

## Silicon N-channel Power F-MOS FET

#### ■ Features

- Low ON resistance  $R_{DS}$  (on) :  $R_{DS}$  (on) = 4.7 $\Omega$  (typ.)
- High switching rate : t<sub>f</sub> = 40ns (typ.)
- No secondary breakdown
- High breakdown voltage

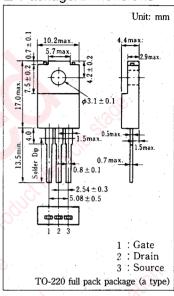
## ■ Application

- No contact relay
- · Solenoid drive
- Motor drive
- Control equipment
- Switching power source

### ■ Absolute Maximum Ratings (Tc=25°C)

Item		Symbol	Value	Unit	
Drain-source voltage	2SK808	·	800	77	
Diani-source voltage	2SK808A	$V_{DSS}$	900	<b>V</b>	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC	I <sub>D</sub>	1	A	
	Peak-to-peak value	I <sub>DP</sub>	3		
Power dissipation	Tc=25℃	$P_{\mathrm{D}}$	45	W	
rower dissipation	Ta=25℃	1 D	2.0	o W	
Channel temperature		$T_{ch}$	150	OC.	
Storage temperature		T <sub>stg</sub>	$-55 \sim +150$	C	

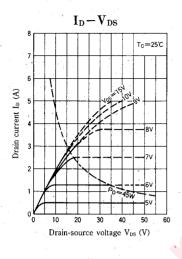
#### ■ Package Dimensions

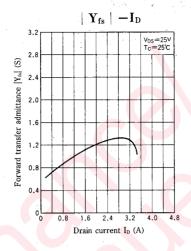


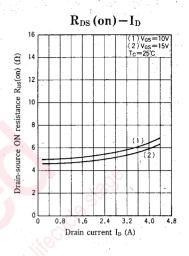
# ■ Electrical Characteristics (Tc=25°C)

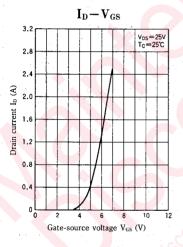
Item		Symbol	Condition	min.	typ.	max.	Unit
Drain current		$I_{DSS}$	$V_{DS} = 640 \text{V}, V_{GS} = 0$	(05.		0.1	mA
Gate-source current		$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0$	4		±1	μА
Drain-source voltage	2SK808	V <sub>DSS</sub>	$I_D = 1 \text{ mA}, V_{GS} = 0$	800			v
	2SK808A			900	7		
Gate threshold voltage		$V_{th}$	$V_{DS}=25V$ , $I_D=1mA$	1		5	V
Drain-source ON resist	ance	R <sub>DS</sub> (on)	$V_{GS} = 10V, I_D = 0.7A$	41	4.7	7.0	Ω
Forward transfer admit	tance	Yfs	$V_{DS} = 25V, I_D = 0.7A$	0.4	0.8		S
Input capacitance		Ciss			380		pF
Output capacitance		Coss	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		75		pF
Reverse transfer capacitance		Crss			35		pF
Turn-on time Fall time Delay time		ton	$V_{GS} = 10V, I_D = 0.7A$ $V_{DD} = 200V, R_L = 285 \Omega$		35		ns
		t <sub>f</sub>			40		ns
		t d (off)			70	i de la	ns

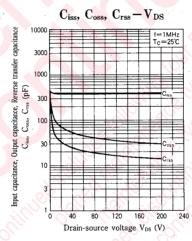


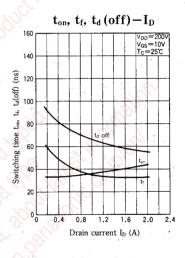


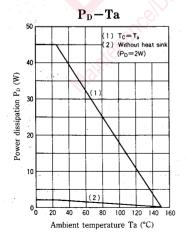


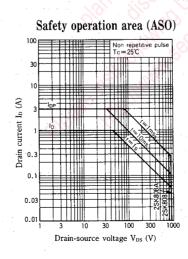


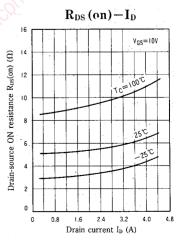












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